

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Sang Ho Lee	08/11/2005
Jong Wook Ju	08/11/2005
Marcos Karnezos	08/09/2005

RECEIVING PARTY DATA

Name:	ChipPac, Inc.
Street Address:	47400 Kato Road
City:	Fremont
State/Country:	CALIFORNIA
Postal Code:	94538

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11134845

CORRESPONDENCE DATA

Fax Number: (650)712-0263

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 650-712-0340

Email: phurley@hmbay.com

Correspondent Name: Bill Kennedy

Address Line 1: Haynes Beffel & Wolfeld LLP

Address Line 2: P.O. Box 366

Address Line 4: Half Moon Bay, CALIFORNIA 94019

NAME OF SUBMITTER:

Bill Kennedy

Total Attachments: 4

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PATENT

REEL: 016396 FRAME: 0081

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**JOINT TO CORPORATE
ASSIGNMENT**

WHEREAS, the undersigned Sang Ho Lee of Yeosu, Republic of Korea; Jong Wook Ju of Kyungman, Republic of Korea; Hyeog Chan Kwon of Seoul, Republic of Korea; and Marcos Karnezos of Palo Alto, California, hereinafter termed the "Inventors" have invented certain new and useful improvements in:

Adhesive/Spacer Island Structure for Stacking Over Wire Bonded Die

and have filed a non-provisional application for United States patent disclosing and identifying the above invention, the said non-provisional application having been filed on May 20, 2005 as U.S. Application No. 11/134,845; and have executed an oath or declaration of inventorship for such non-provisional application on:

the 9th day of August, 2005,

hereinafter termed the "Applications"; and

WHEREAS, ChipPAC, Inc., a corporation of the state of Delaware, having a place of business at 47400 Kato Road, Fremont, California 94538 (hereinafter termed the "Assignee") is desirous of acquiring the entire right, title and interest in and to the Applications and the invention disclosed therein, and in and to any and all embodiments of the invention, heretofore conceived, made, or discovered jointly or severally by said Inventors (all collectively hereinafter termed the "Invention") and in and to any and all patents, inventors' certificates, and other forms of protection (hereinafter termed the "Patents") thereon granted in the United States and foreign countries.

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged by the Inventors:

1. The Inventors have assigned to the Assignee, and do hereby sell, assign, transfer and convey to the Assignee all right, title and interest (a) in and to the Invention and the Applications; and (b) in and to all rights to apply for foreign patents (including patent, utility model and industrial designs) on the Invention pursuant to the International Convention for the Protection of Industrial Property or otherwise, including the right to claim priority from the Applications; and (c) in and to any and all applications filed and any and all patents granted on the Invention in the United States or any foreign country, including each and every application filed and each and every patent granted on any application which is a divisional, substitution, continuation, or continuation-in-part of any of said applications; and (d) in and to each and every reissue or extension of any of said patents.

2. The Inventors hereby covenant and agree to cooperate with the Assignee to enable the Assignee to enjoy to the fullest extent the right, title and interest herein conveyed in the United States and foreign countries. Such cooperation by the Inventors shall include prompt production of pertinent facts and documents, giving of testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by the Assignee (a) for perfecting in the Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering the Invention; (d) for filing and prosecuting applications for reissuance of any said Patents; (e) for interference or other priority proceedings involving the Invention, and (f) for legal proceedings involving the Invention and any applications therefor and any patents granted thereon, including without limitation reissues and reexaminations, opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by the Inventors in providing such cooperation shall be paid for by the Assignee.

3. The terms and covenants of this assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representatives, and shall be binding upon the Inventors, their heirs, legal representatives and assigns.

4. The Inventors hereby warrant and represent that they have not entered into and will not enter into any assignment, contract, or understanding in conflict herewith.

IN TESTIMONY WHEREOF, the Inventors have executed and delivered this instrument to the Assignee as of the date[s] written below.

Sang Ho Lee

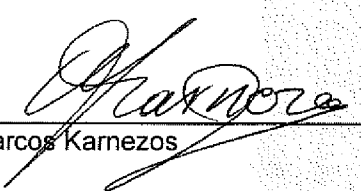
Date

Jong Wook Ju

Date

Hyeog Chan Kwon

Date



Marcos Kamezos

Date

Aug. 9, 2005

**JOINT TO CORPORATE
ASSIGNMENT**

WHEREAS, the undersigned Sang Ho Lee of Yeosu, Republic of Korea; Jong Wook Ju of Kyungman, Republic of Korea; Hyeog Chan Kwon of Seoul, Republic of Korea; and Marcos Karnezos of Palo Alto, California, hereinafter termed the "Inventors" have invented certain new and useful improvements in:

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and have filed a non-provisional application for United States patent disclosing and identifying the above invention, the said non-provisional application having been filed on May 20, 2005 as U.S. Application No. 11/134,845; and have executed an oath or declaration of inventorship for such non-provisional application on:

the 11th day of August, 2005,

hereinafter termed the "Applications"; and

WHEREAS, ChipPAC, Inc., a corporation of the state of Delaware, having a place of business at 47400 Kato Road, Fremont, California 94538 (hereinafter termed the "Assignee") is desirous of acquiring the entire right, title and interest in and to the Applications and the invention disclosed therein, and in and to any and all embodiments of the invention, heretofore conceived, made, or discovered jointly or severally by said Inventors (all collectively hereinafter termed the "Invention") and in and to any and all patents, inventors' certificates, and other forms of protection (hereinafter termed the "Patents") thereon granted in the United States and foreign countries.

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2. The Inventors hereby covenant and agree to cooperate with the Assignee to enable the Assignee to enjoy to the fullest extent the right, title and interest herein conveyed in the United States and foreign countries. Such cooperation by the Inventors shall include prompt production of pertinent facts and documents, giving of testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by the Assignee (a) for perfecting in the Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering the Invention; (d) for filing and prosecuting applications for reissuance of any said Patents; (e) for interference or other priority proceedings involving the Invention; and (f) for legal proceedings involving the Invention and any applications therefor and any patents granted thereon, including without limitation reissues and reexaminations, opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by the Inventors in providing such cooperation shall be paid for by the Assignee.

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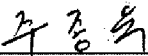
IN TESTIMONY WHEREOF, the Inventors have executed and delivered this instrument to the Assignee as of the date[s] written below.



Sang Ho Lee

08.11.05


Date



Jong Wook Ju

08.11.05

Date



Hyeog Chan Kwon

AUG 11 / 05

Date

Marcos Karnezos

Date